



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2018-03-23
<b>Company Unique ID</b>	NL 008751171801		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Floriana SAN BIAGIO	<b>Representative Title</b>	AMS MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	EB6R*V524AAY	A	ZY1A	2018-03-23
Amount	UoM	Unit type	ST ECOPACK Grade	
54.82	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Tin - 3.5Ag	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	5x4.4x0.9	14	gull wing	
Comment	6R TSSOP 14 BODY 4.4 PITCH 0.65; MDF valid for TSV524IYPT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	EB6R*V524AAY				4999998.0	999982.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	0.708	mg	supplier	die	Silicon (Si)	7440-21-3		0.677	mg	956215	12350
				supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	8475	109
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	1412	18
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	1412	18
				supplier	Passivation	Silicon Nitride	12033-89-5		0.002	mg	2825	36
				supplier	Passivation	Silicon Oxide	7631-86-9		0.012	mg	16949	219
Leadframe	M-004 Copper and its alloys	31.185	mg	supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.009	mg	12712	164
				supplier	alloy	Copper (Cu)	7440-50-8		29.248	mg	937887	533528
				supplier	alloy	Iron (Fe)	7439-89-6		0.705	mg	22607	12860
				supplier	alloy	Zinc (Zn)	7440-66-6		0.035	mg	1122	638
				supplier	alloy	Iron Phosphide (Fe2P)	7723-14-0		0.009	mg	289	164
				supplier	metallization	Silver(Ag)	7440-22-4		1.188	mg	38095	21671
Die attach	M-015 Other organic materials	0.680	mg	supplier	glue	Silver (Ag)	7440-22-4		0.305	mg	448529	5564
				supplier	glue	Bisphenol F type epoxy resin	9003-36-5		0.030	mg	44118	547
				supplier	glue	Epoxy resin	68475-94-5		0.011	mg	16176	201
				supplier	glue	2,6-Diglycidyl phenyl allyl ether	EC 417-470-1		0.011	mg	16176	201
				supplier	glue	Gamma Butyrolactone	96-48-0		0.011	mg	16176	201
				supplier	glue	Polyoxypropylenediamine	9046-10-0		0.011	mg	16176	201
Encapsulation	M-015 Other organic materials	20.860	mg	supplier	wire	Gold (Au)	7440-57-5		0.301	mg	442647	5491
				supplier	molding compound	Epoxy resin	29690-82-2		2.086	mg	100000	38052
				supplier	molding compound	Phenol resin	25068-38-6		1.042	mg	49952	19008
				supplier	molding compound	Silica, vitreous	60676-86-0		17.627	mg	845014	321543
Finishing	M-011 Other inorganic materials	1.386	mg	supplier	molding compound	Carbon black	1333-86-4		0.105	mg	5034	1915
				supplier	connection coating	Tin (Sn)	7440-31-5		1.386	mg	1000000	25283